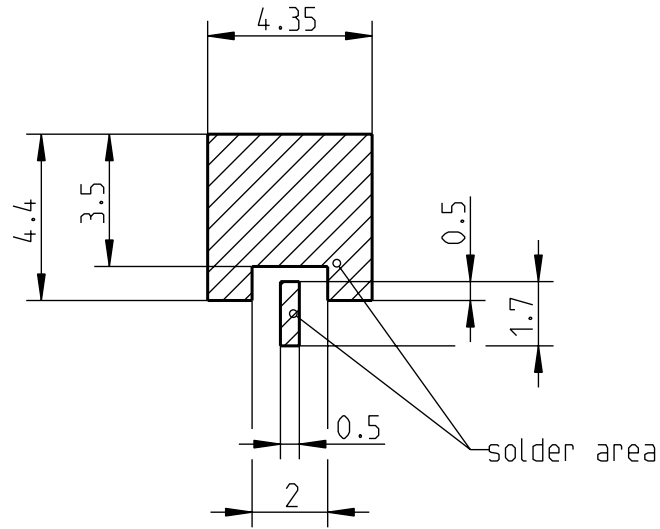


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Leiterplatten-Layout
PCB layout
B 124



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

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Format: TCC-FB-05-PL-A4-Einzelteil
Date: 15.11.2011 10:58:49
Version: 1.1

Dimensions in mm



ISO-Projektion Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		<i>general tolerance</i> ISO 2768 RN 006-01 m-H dimensions <0,5 and symmetry		<i>scale:</i> 5:1 () 2	
				<i>material:</i>	
				<i>date</i>	<i>name</i>
			<i>drawn</i>	14.11.2005	A_Nobis
			<i>check</i>	20.10.2011	E_Schwangler
			<i>appr.</i>	20.10.2011	E_Schwangler
<i>dimensioning incl. finish</i>					
				<i>title:</i>	
				Leiterplatten-Layout PCB layout	
				<i>drawing-no...:</i>	
				MB_124	
				<i>sheet:</i>	
				1	
				<i>of:</i>	
				1	
<i>rev.</i>	<i>change-no</i>	<i>name</i>	<i>date</i>	<i>distribu-</i>	<i>tion to:</i>
b00	11-0980	B_Wollitzer	20.10.2011	FE	AZ QSM RMT .
a00	05-0615	A_Nobis	15.11.2005	X
<i>remarks:</i> .					